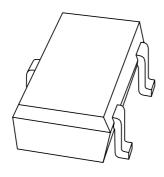
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



## PMST5088; PMST5089 NPN general purpose transistors

Product data sheet Supersedes data of 1997 May 22 1999 Apr 22



## NPN general purpose transistors

PMST5088; PMST5089

#### **FEATURES**

• Low current (max. 100 mA)

• Low voltage (max. 30 V).

#### **APPLICATIONS**

• Low-noise input stages in audio equipment.

#### **DESCRIPTION**

NPN transistor in a SC-70; SOT323 plastic package.

#### **MARKING**

TYPE NUMBER	MARKING CODE(1)
PMST5088	*1Q
PMST5089	*1R

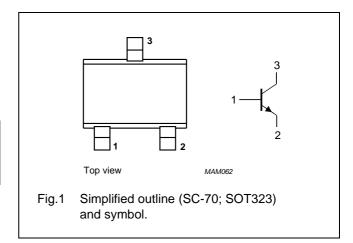
#### Note

1. \* = -: Made in Hong Kong.

\* = t : Made in Malaysia.

#### **PINNING**

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	PMST5088		_	35	V
	PMST5089		_	30	V
V <sub>CEO</sub>	collector-emitter voltage	open base			
	PMST5088		_	30	V
	PMST5089		_	25	V
V <sub>EBO</sub>	emitter-base voltage	open collector	_	4.5	V
I <sub>C</sub>	collector current (DC)		-	100	mA
I <sub>CM</sub>	peak collector current		_	200	mA
$I_{BM}$	peak base current		_	100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	-	200	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

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#### Note

1. Transistor mounted on an FR4 printed-circuit board.

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## NPN general purpose transistors

PMST5088; PMST5089

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	625	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V	_	50	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V; T <sub>j</sub> = 150 °C	_	10	μΑ
I <sub>EBO</sub>	emitter cut-off current	I <sub>C</sub> = 0; V <sub>EB</sub> = 3 V	_	50	nA
		I <sub>C</sub> = 0; V <sub>EB</sub> = 4.5 V	_	100	nA
h <sub>FE</sub>	DC current gain	V <sub>CE</sub> = 5 V			
	PMST5088	$I_C = 0.1 \text{ mA}$	300	900	
		$I_C = 1 \text{ mA}$	350	_	
		I <sub>C</sub> = 10 mA	300	_	
	DC current gain	V <sub>CE</sub> = 5 V			
	PMST5089	$I_C = 0.1 \text{ mA}$	400	1200	
		$I_C = 1 \text{ mA}$	450	_	
		I <sub>C</sub> = 10 mA	400	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	I <sub>C</sub> = 10 mA; I <sub>B</sub> = 1 mA	_	500	mV
$V_{BE}$	base-emitter voltage	$I_C = 10 \text{ mA}; V_{CE} = 5 \text{ V}$	_	800	mV
C <sub>c</sub>	collector capacitance	$I_E = i_e = 0$ ; $V_{CB} = 5 \text{ V}$ ; $f = 1 \text{ MHz}$	_	4	pF
C <sub>e</sub>	emitter capacitance	$I_C = I_c = 0$ ; $V_{EB} = 0.5 \text{ V}$ ; $f = 1 \text{ MHz}$	_	12	pF
f <sub>T</sub>	transition frequency	$I_C = 10 \text{ mA}; V_{CE} = 5 \text{ V}; f = 100 \text{ MHz}$	100	_	MHz
F	noise figure	$I_C = 100 \mu A; V_{CE} = 5 V; R_S = 1 k\Omega$			
	PMST5088	f = 10 Hz to 15.7 kHz	_	3	dB
	PMST5089		_	2	dB

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## NPN general purpose transistors

PMST5088; PMST5089

EUROPEAN PROJECTION

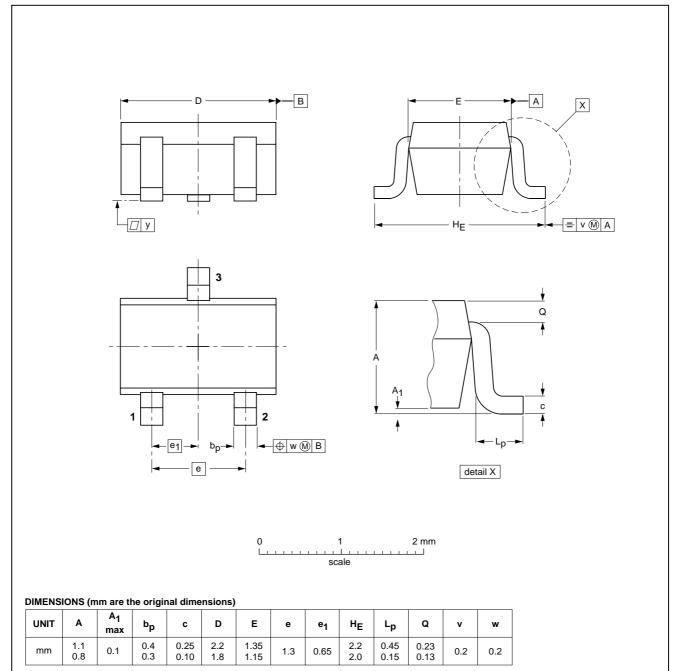
ISSUE DATE

97-02-28

#### **PACKAGE OUTLINE**

Plastic surface mounted package; 3 leads

**SOT323** 



**REFERENCES** 

EIAJ

SC-70

**JEDEC** 

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IEC

OUTLINE

VERSION

SOT323

### **NPN** general purpose transistors

PMST5088; PMST5089

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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